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Declarations under Rule 4.17:

- as to applicant's entitlement to apply for and be granted a patent (Rule 4.17(ii))

(54) **Title:** IMPEDANCE CONTROLLED METALLIZED PLASTIC SOCKET

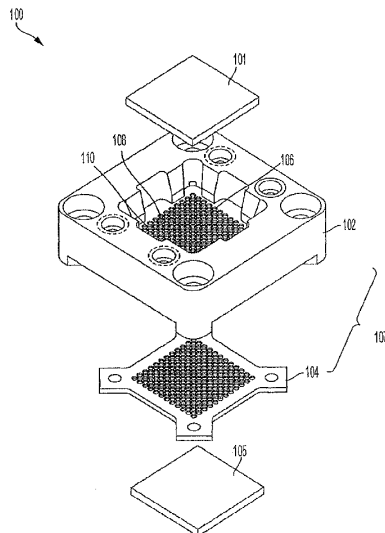


FIG. 1

(57) **Abstract:** Methods, systems, and apparatus for an electrical connector assembly for connecting an integrated circuit chip to a printed circuit board. The electrical connector assembly includes a socket body that is made of an insulating material. The socket body has a top surface, a bottom surface, and a first plurality of cavities including a first cavity and a second cavity. The first cavity and the second cavity each have an inner surface plated with a conductive material to form a metal grounding shell. The electrical connector assembly includes multiple probes including a first probe and a second probe. The first probe is configured to be positioned within the first cavity and the second probe is configured to be positioned within the second cavity. The electrical connector assembly includes one or more signal traces that electrically connect the metal grounding shells of the first cavity and the second cavity.

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